



Statement of Materials, Construction

100L LQFP TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Ag Plated Cu	0.28700	Cu	7440-50-8	0.27314	41.11232	95.17
				Fe	7439-89-6	0.00057	0.08640	0.20
				Zn	7440-32-6	0.00052	0.07776	0.18
				Pb	7439-92-1	0.00014	0.02160	0.05
				Ni	7440-02-0	0.00918	1.38236	3.20
				Mn	7439-96-5	0.00029	0.04320	0.10
				Si	7440-21-3	0.00208	0.31319	0.73
				Silver (plating)	7440-22-4	0.00057	0.08640	0.20
2	Die	Silicon Chip	0.02500	Mg	7439-95-4	0.00050	0.07560	0.18
				Si	7440-21-3	0.02488	3.74415	99.50
3	Die Attach Material	Conductive Epoxy	0.00800	Epoxy Resin	Proprietary	0.00120	0.18062	15.00
				Silver	7440-22-4	0.00636	0.95730	79.50
				Aromatic Amine	Proprietary	0.00044	0.06623	5.50
4	Wire	Gold	0.00125	Au	7440-57-5	0.00125	0.18813	99.99
5	Lead Finish	Alloy	0.04212	Pb	7439-92-1	0.00421	0.63398	10.00
				Sn	7440-31-5	0.03791	5.70586	90.00
6	Encapsulation	Epoxy Resin	0.30100	Fused Silica	60676-86-0	0.24592	37.01507	81.70
				Brominated Epoxy Resin	68541-56-0	0.00452	0.67959	1.50
				Carbon Black	1333-86-4	0.00090	0.13592	0.30
				Epoxy Resin	Proprietary	0.02258	3.39796	7.50
				Phenol Resin	Proprietary	0.02258	3.39796	7.50
				Antimony Trioxide	1309-64-4	0.00452	0.67959	1.50
Total Package Weight			0.66437					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (Maximum Allowable Limit (wt %))	
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%